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USE OF MULTIPLE-VELVETS WOVEN TEXTILES FOR NOVELTY MULTI-COMPONENT TESTING THE THICKNESS OF ELECTRONIC APPLICATIONS

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In this paper, the use of woven textile structures for multi-component testing of the thickness of electronic circuits is investigated. The advantages and limitations of single and multiple multiple-velvets woven textiles and novel woven structures are analysed. The use of textile velvets woven textiles based conducting yarn and its characteristics are discussed. Details of the development of touch control woven fabric velvets woven textiles are illustrated. The developed multi-component testing the thickness of electronic are fully flexible structures retaining the unique characteristics of textile fabrics, Novel solutions for improving the connectivity of conducting yarns in woven structures; a method and device for the insertion of flexible electronic circuits in woven fabric pockets are also discussed. Results of testing and evaluation of the performance of the fabric multi-component testing the thickness of electronic are also presented.

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